

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property
Organization

International Bureau

(43) International Publication Date
26 December 2024 (26.12.2024)



(10) International Publication Number
WO 2024/263864 A3

(51) International Patent Classification:

C08G 65/48 (2006.01) C08L 71/12 (2006.01)
C08F 283/08 (2006.01) C08F 283/06 (2006.01)

LU, LV, MC, ME, MK, MT, NL, NO, PL, PT, RO, RS, SE,
SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN,
GQ, GW, KM, ML, MR, NE, SN, TD, TG).

(21) International Application Number:

PCT/US2024/034942

Published:

— with international search report (Art. 21(3))

(22) International Filing Date:

21 June 2024 (21.06.2024)

(88) Date of publication of the international search report:

08 May 2025 (08.05.2025)

(25) Filing Language:

English

(26) Publication Language:

English

(30) Priority Data:

63/509,663 22 June 2023 (22.06.2023) US

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(81) Designated States (unless otherwise indicated, for every
kind of national protection available): AE, AG, AL, AM,
AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ,
CA, CH, CL, CN, CO, CR, CU, CV, CZ, DE, DJ, DK, DM,
DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT,
HN, HR, HU, ID, IL, IN, IQ, IR, IS, IT, JM, JO, JP, KE, KG,
KH, KN, KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU, LY,
MA, MD, MG, MK, MN, MU, MW, MX, MY, MZ, NA,
NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO,
RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, ST, SV, SY, TH,
TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, WS,
ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every
kind of regional protection available): ARIPO (BW, CV,
GH, GM, KE, LR, LS, MW, MZ, NA, RW, SC, SD, SL, ST,
SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ,
RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ,
DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT,

(54) Title: THERMOSETTING COMPOSITIONS, CURED COMPOSITIONS, AND PREPREGS AND LAMINATES BASED ON
SAME

(57) Abstract: This disclosure relates to thermosetting compositions suitable for use in making electronic materials such as circuit board
substrates, as well as cured compositions, prepregs and laminates based on such thermosetting compositions. One aspect of the disclosure
is a thermosetting composition comprising: a poly(1,4-phenylene ether) component having at least 80% phenylene ether content, the
poly(1,4-phenylene ether) component being a poly(1,4-phenylene ether) bis(meth)acrylate component, a bis(vinyl) poly(1,4-phenylene
ether) component, or a bis((meth)allyl) poly(1,4-phenylene ether) component, or a combination of two or more thereof; an aromatic
crosslinking component having a weight average molecular weight of no greater than 700 g/mol and bearing on numerical average in
the range of 1.75 - 3.5 crosslinkable vinyl, (meth)allyl and/or (meth)acrylate groups per molecule; a butadiene/styrene copolymeric
rubber component; microparticulate silica; a halogen-free organic fire retardant component; and an effective amount of a thermal free-
radical initiator component.

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